



Material Content Data Sheet



Sales Product Name		BSZ060NE2LS		Issued		20. July 2018		
MA#		MA001258248						
Package		PG-TSDSON-8-25		Weight*		34.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.182	0.53	0.53	5291	5291
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		106	
	non noble metal	zinc	7440-66-6	0.015	0.04		423	
	non noble metal	iron	7439-89-6	0.291	0.85		8454	
wire	non noble metal	copper	7440-50-8	11.804	34.33	35.23	343251	352234
	noble metal	gold	7440-57-5	0.031	0.09	0.09	908	908
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1064
plastics	plastics	epoxy resin	-	1.884	5.48		54779	
	inorganic material	silicondioxide	60676-86-0	16.369	47.60	53.19	475989	531832
leadfinish	non noble metal	tin	7440-31-5	0.395	1.15	1.15	11494	11494
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	591	591
solder	noble metal	silver	7440-22-4	0.008	0.02		234	
	non noble metal	tin	7440-31-5	0.006	0.02		187	
	non noble metal	lead	7439-92-1	0.307	0.89	0.93	8930	9351
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		106	
	non noble metal	iron	7439-89-6	0.073	0.21		2119	
	non noble metal	copper	7440-50-8	2.959	8.60	8.82	86048	88299
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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